Silicon P Channel MOS FET High Speed Power Switching

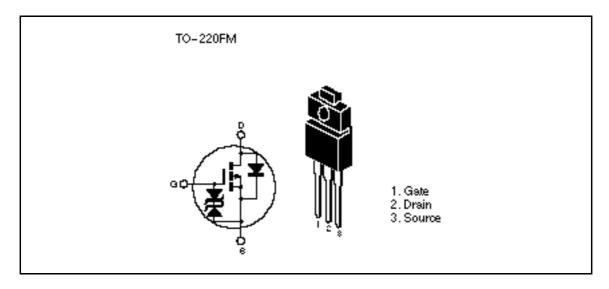


ADE-208-639A (Z) 2nd. Edition Jun 1998

Features

- Low on-resistance $R_{DS(on)} = 0.075$ typ.
- Low drive current.
- 4V gate drive devices.
- High speed switching.

Outline





Absolute Maximum Ratings (Ta = 25° C)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	-60	V	
Gate to source voltage	V _{GSS}	±20	V	
Drain current	I _D	-15	А	
Drain peak current	Note1 D(pulse)	-60	А	
Body-drain diode reverse drain current	I _{DR}	-15	А	
Avalanche current	AP Note3	-15	А	
Avalanche energy	E _{AR} ^{Note3}	19	mJ	
Channel dissipation	Pch Note2	30	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	
Natar A DW 40-12 date and 40	1			

Note: 1. PW 10µs, duty cycle 1 %

2. Value at Tc = 25°C

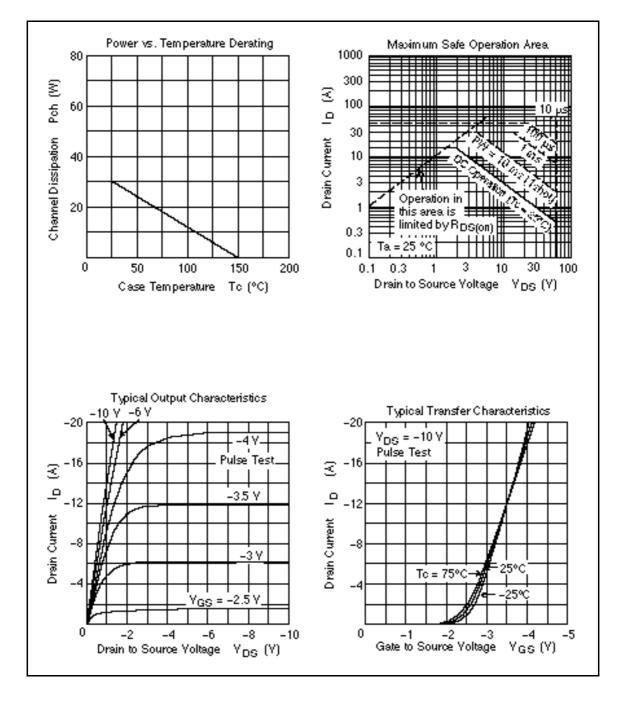
3. Value at Tch = 25° C, Rg 50

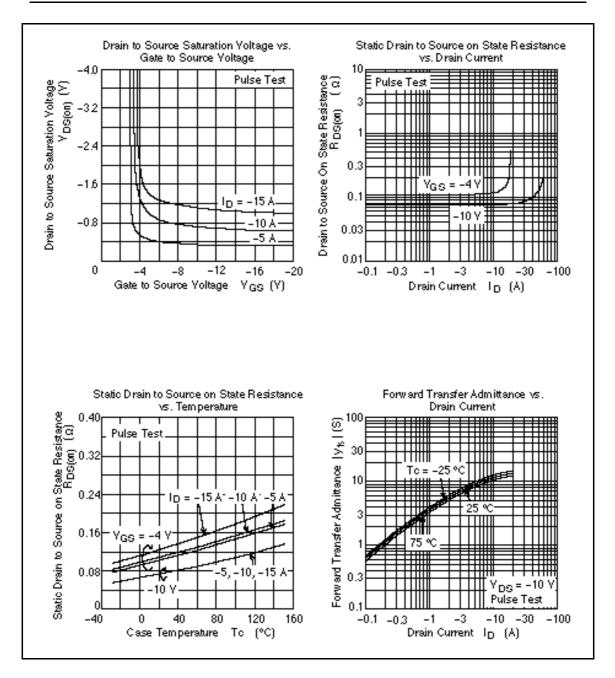
Electrical Characteristics (Ta = 25°C)

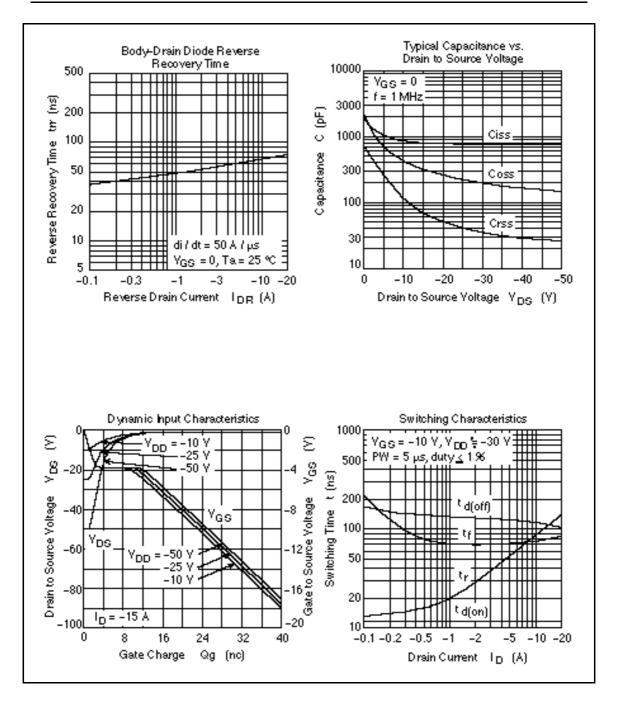
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-60		_	V	$I_{\rm D} = -10 {\rm mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{g} = \pm 100 \mu A, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}		—	-10	μA	$V_{\rm DS} = -60 \text{V}, V_{\rm GS} = 0$
Gate to source leak current	I _{GSS}		—	±10	μA	$V_{GS} = \pm 16V, V_{DS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	-1.0	_	-2.0	V	$I_{\rm D} = -1$ mA, $V_{\rm DS} = -10$ V
Static drain to source on state	$R_{DS(on)}$		0.075	0.095		$I_{\rm D} = -8A, V_{\rm GS} = -10V^{\rm Note4}$
resistance	R _{DS(on)}		0.105	0.155		$I_{\rm D} = -8A, V_{\rm GS} = -4V^{\rm Note4}$
Forward transfer admittance	y _{fs}	6.5	11	_	S	$I_{\rm D}$ = -8A, $V_{\rm DS}$ = -10V ^{Note4}
Input capacitance	Ciss		850	—	pF	$V_{DS} = -10V$
Output capacitance	Coss		420	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	110	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}		12	—	ns	$V_{GS} = -10V, I_{D} = -8A$
Rise time	t,		75	—	ns	R _L =3.75
Turn-off delay time	$t_{d(off)}$		125	_	ns	-
Fall time	t _f		75	_	ns	_
Body-drain diode forward voltage	V_{DF}	_	-1.1	_	V	$I_{\rm F} = -15$ A, $V_{\rm GS} = 0$
Body–drain diode reverse recovery time	t _{rr}		70	_	ns	$I_F = -15A, V_{GS} = 0$ diF/ dt =50A/µs

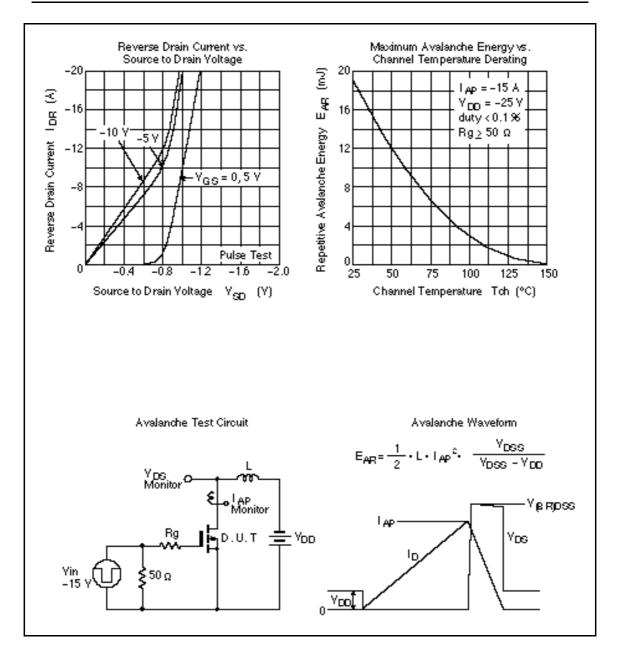
Note: 4. Pulse test

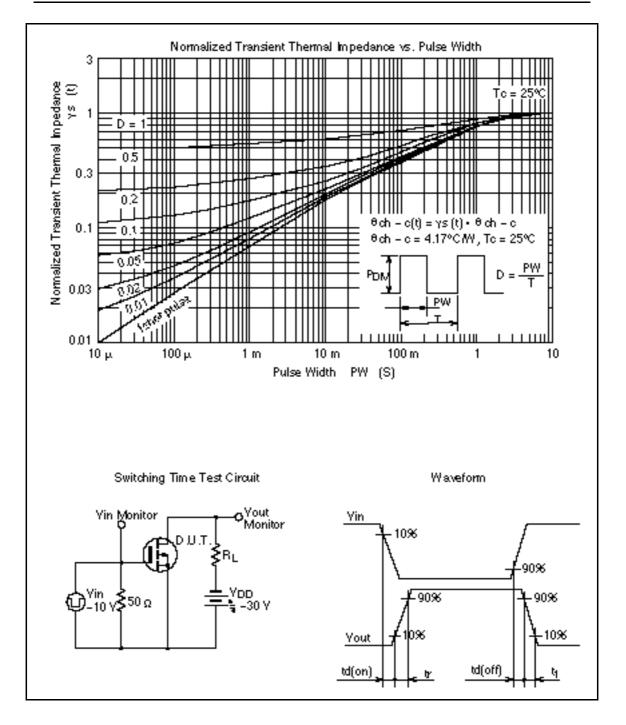
Main Characteristics





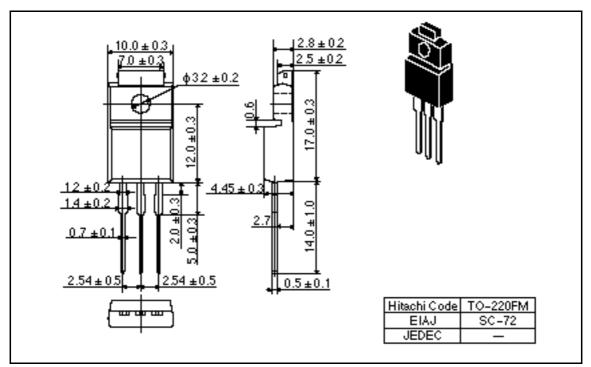






Package Dimensions





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